TOSHIBA Field Effect Transistor Silicon P Channel MOS Type (L^2 - π -MOSV)

2SJ401

DC-DC Converter, Relay Drive and Motor Drive Applications

• 4-V gate drive

• Low drain-source ON resistance : $RDS(ON) = 33 \text{ m}\Omega \text{ (typ.)}$

• High forward transfer admittance $: |Y_{fs}| = 20 \text{ S (typ.)}$

• Low leakage current $: I_{DSS} = -100 \,\mu\text{A} \,(\text{max}) \,(\text{V}_{DS} = -60 \,\text{V})$

• Enhancement mode : $V_{th} = -0.8 \sim -2.0 \text{ V (V}_{DS} = -10 \text{ V, I}_{D} = -1 \text{ mA})$

Maximum Ratings (Ta = 25°C)

Characteris	stics	Symbol	Rating	Unit	
Drain-source voltage		V_{DSS}	-60	V	
Drain-gate voltage (Ro	_{GS} = 20 kΩ)	V_{DGR}	-60	V	
Gate-source voltage		V_{GSS}	±20	٧	
Drain current	DC (Note 1)	I _D	-20	Α	
	Pulse(Note 1)	I _{DP}	-80	Α	
Drain power dissipation	n (Tc = 25°C)	P_{D}	100	W	
Single pulse avalanche	e energy (Note 2)	E _{AS}	800	mJ	
Avalanche current		I _{AR}	-20	Α	
Repetitive avalenche e	energy (Note 3)	E _{AR}	10	mJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature ra	ange	T _{stg}	-55~150	°C	

Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	1.25	°C/W
Thermal resistance, channel to ambient	R _{th (ch-a)}	83.3	°C/W

Note 1: Ensure that the channel temperature does not exceed 150°C.

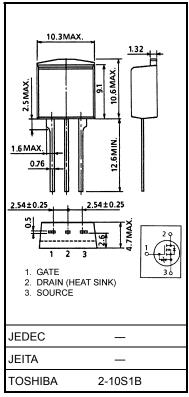
Note 2: V_{DD} = -50 V, T_{ch} = 25°C (initial), L = 1.44 mH, R_G = 25 Ω , I_{AR} = -20 A

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

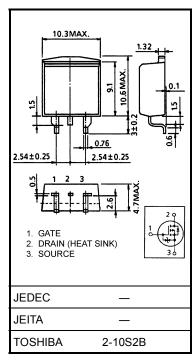
This transistor is an electrostatic-sensitive device.

Please handle with caution.





Weight: 1.5 g (typ.)



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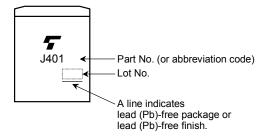
Electrical Characteristics (Ta = 25°C)

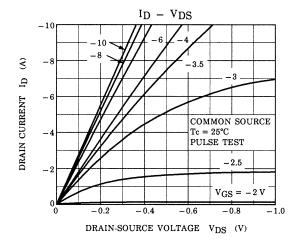
Charac	eteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	rrent	I _{GSS}	V _{GS} = ±16 V, V _{DS} = 0 V	_	_	±10	μΑ
Drain cut-off cu	rrent	I _{DSS}	V _{DS} = -60 V, V _{GS} = 0 V	_	_	-100	μΑ
Drain-source br	eakdown voltage	V (BR) DSS	$I_D = -10 \text{ mA}, V_{GS} = 0 \text{ V}$	-60	_	_	V
Gate threshold v	roltage	V _{th}	V _{DS} = -10 V, I _D = -1 mA	-0.8	_	-2.0	V
Drain-source ON resistance		R _{DS} (ON)	V _{GS} = -4 V, I _D = -10 A		50	90	m0
			V _{GS} = -10 V, I _D = -10 A	_	33	45	mΩ
Forward transfer	admittance	Y _{fs}	V _{DS} = -10 V, I _D = -10 A	10	20	_	S
Input capacitano	e	C _{iss}		_	2800	_	
Reverse transfer capacitance		C _{rss}	$V_{DS} = -10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		450	_	рF
Output capacitance		Coss		_	1300	_	
Switching time	Rise time	t _r	$V_{GS} = 10V$ $V_{GS} = 10V$ $V_{GS} = 10V$ $R_{L} = 3\Omega$	_	15	_	ns ns
	Turn-on time	t _{on}		_	35	_	
	Fall time	t _f		_	25	_	
	Turn-off time	t _{off}	$V_{\mathrm{DD}} = -30 \mathrm{V}$ Duty $\leq 1\%$, $t_{\mathrm{W}} = 10 \mu\mathrm{s}$	_	120	_	
Total gate charge (Gate-source plus gate-drain)		Qg		_	90		nC
Gate-source charge		Q _{gs}	$V_{DD} \approx -48 \text{ V}, V_{GS} = -10 \text{ V}, I_D = -20 \text{ A}$		65		
Gate-drain ("miller") charge		Q_{gd}]		25		

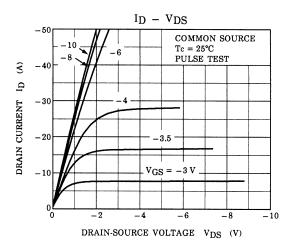
Source-Drain Ratings and Characteristics (Ta = 25°C)

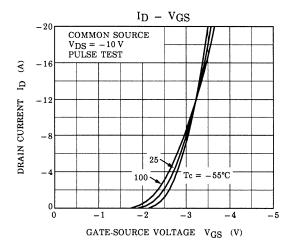
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	_	_	_	-20	Α
Pulse drain reverse current (Note 1)	I _{DRP}	_	_	_	-80	Α
Forward voltage (diode)	V _{DSF}	I _{DR} = -20 A, V _{GS} = 0 V	_	_	1.7	V
Reverse recovery time	t _{rr}	I _{DR} = -20 A, V _{GS} = 0 V dI _{DR} / dt = 50 A / µs	_	75		ns
Reverse recovery charge	Qrr	dl _{DR} / dt = 50 A / μs		83		nC

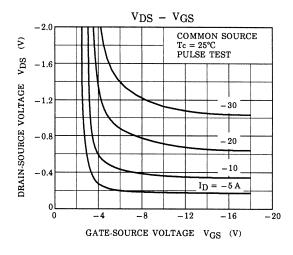
Marking

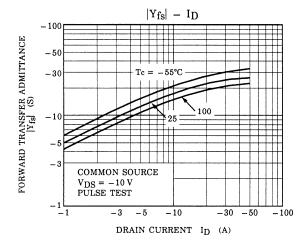


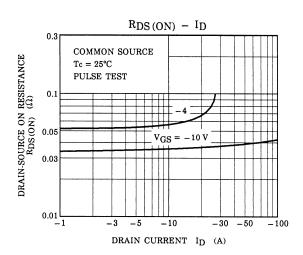




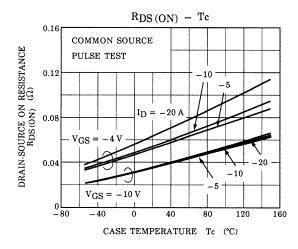


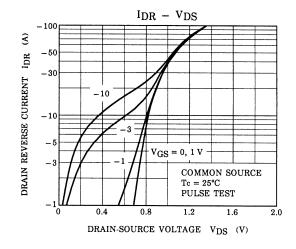


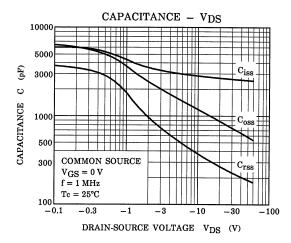


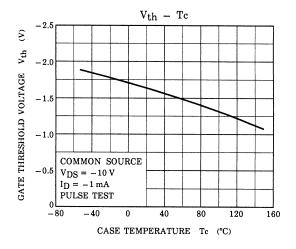


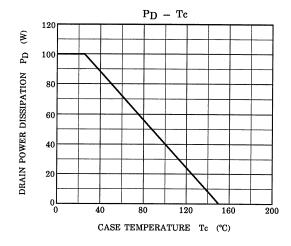
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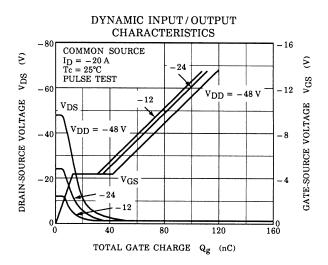


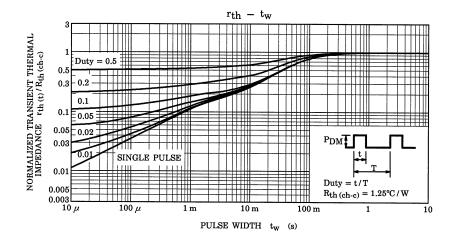


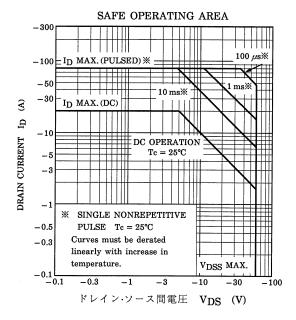


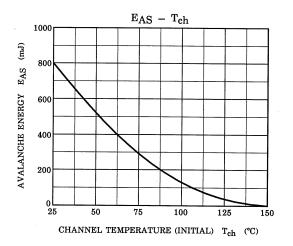


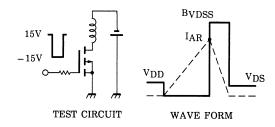












$$\begin{split} &R_G\!=\!25\Omega\\ &V_{DD}\!=\!-50V,\;L\!=\!1.44mH \end{split}$$

$$E_{\mbox{\scriptsize AS}} \!=\! \frac{1}{2} \cdot L \cdot I^2 \cdot (\frac{B_{\mbox{\scriptsize VDSS}}}{B_{\mbox{\scriptsize VDSS}} - V_{\mbox{\scriptsize DD}}})$$

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Handbook" etc..

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